G2C+

T STRATEGY ALLIANCE

2467.TW
c sun志聖

5443.TW
GPM均豪

6640.TW
GMM均華

Forward-looking Statement

- Information included in this presentation that are not historical in nature are "forward looking statements“. C Sun cautions readers that forward looking statements are based on C Sun’s reasonable knowledge and current expectations and are subject to various risks and uncertainties.

- Actual results may differ materially from those contained in such forward looking statements for a variety of reasons including without limitation, risks associated with demand and supply change, manufacturing and supply capacity, design win, time to market, market competition, industrial cyclicality, customer’s financial condition, exchange rate fluctuation, legal actions, amendments of the laws and regulations, global economy change, natural disasters, and other unexpected events which may disrupt C Sun’s business and operations.

- Accordingly, readers should not place reliance on any forward looking statements. Except as required by law, C Sun undertakes no obligation to update any forward looking statement, whether as a result of new information, future events, or otherwise.

Business Philosophy-

ALL WIN

G2C+

合力共創 同行致遠

Well-intentioned motives lead careers to success

---From 『Heart』 Inamori Kazuo

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C Sun Mfg Ltd.

Stock No. 2467.TW c sun志聖

Investor's Meeting

2025.5.19

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T STRATEGY ALLIANCE

The Alloance Members: 1700+

R&D personnel: 560+

R&D personnel account for 32.5%

Since 1966	Since 1978	Since 1978
csun志聖	**GPM均豪精密**	**GMM均華精密**
Thermal (熱) Bonder (壓合) Lamination (貼膜) Peeling (撕膜) UV/Plasma (光/電漿)	AOI (檢測) Metrology (量測) Grinding (研磨) Polishing (拋光)	Die Attach (黏晶) Chip Sorter (揀晶) Auto Jig Saw (切單挑揀)

Core Technologies & Alliance Synergy

c sun
Bonder
Lamination
Peeling
Thermal

GPM
AOI
Metrology
Grinding
Polishing

GMM
Die Attach
Chip Sorter
Auto Jig Saw

Advanced packaging

IC Substrate 、 HBM Packaging 、 2.5/3DIC

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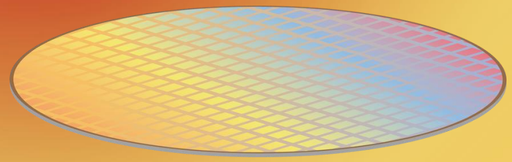

c sun GPM

Foundry

Reclaim wafer

Four Phases of AI Development

Perceptual AI

Perceive images, sounds, and environmental information

2012 年

AlexNet

NVIDIA

Generative AI

Content Generation (Language、Image)

Chat GPT

Gemini

ANTHROPIC

Deepseek

Reasoning AI

Understand Rules
Use Tools
Solve Problems

AI Agent

Deepseek

Physical AI

Possesses Causal Reasoning Physical Intuition

NVIDIA Cosmos AI

NVIDIA

(2025 The Hill and Valley Forum)

Taiwan’s West Golden Corridor: AI Chips

The Shining Diamond Chain of Advanced Packaging Processes

Taiwan's Market Share in **Packaging and Testing** by Value

58.6 %

Taiwan's Market Share in **Wafer Manufacturing** by Value

76.8 %

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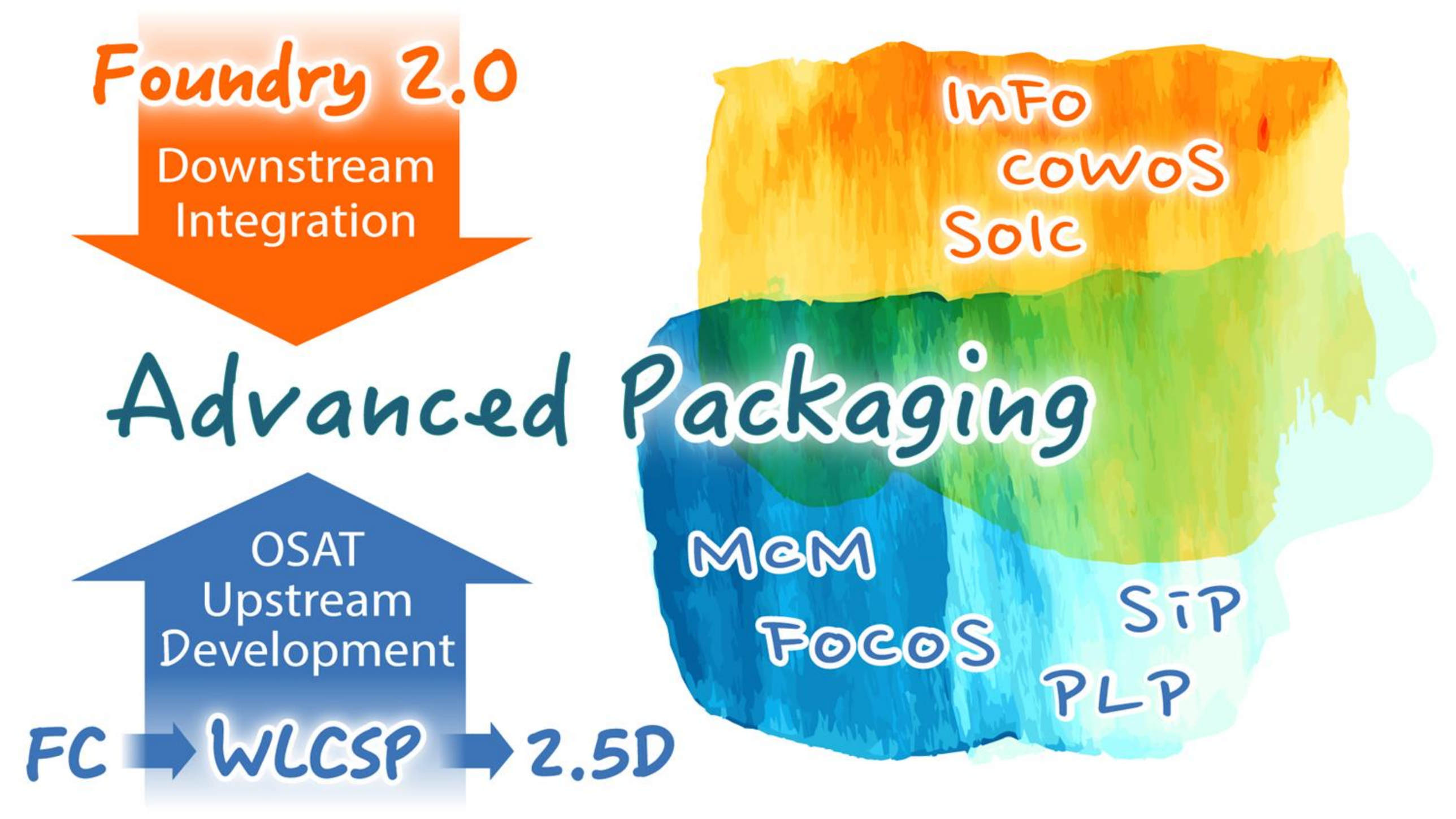
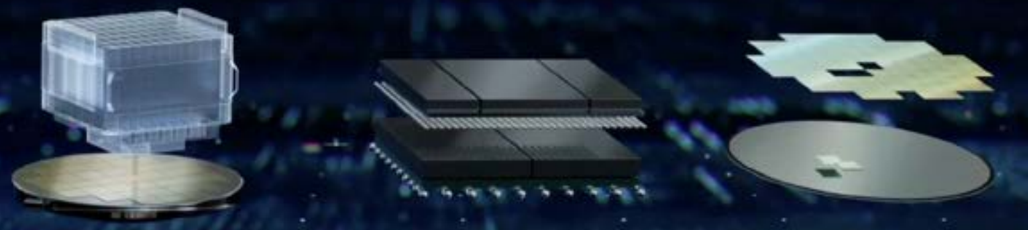

Foundry 2.0
Downstream
Integration
InFO
CoWoS
SoIC
Advanced Packaging
MoM
FoCoS
SiP
PLP
OSAT
Upstream
Development
FC
WLCSP
2.5D

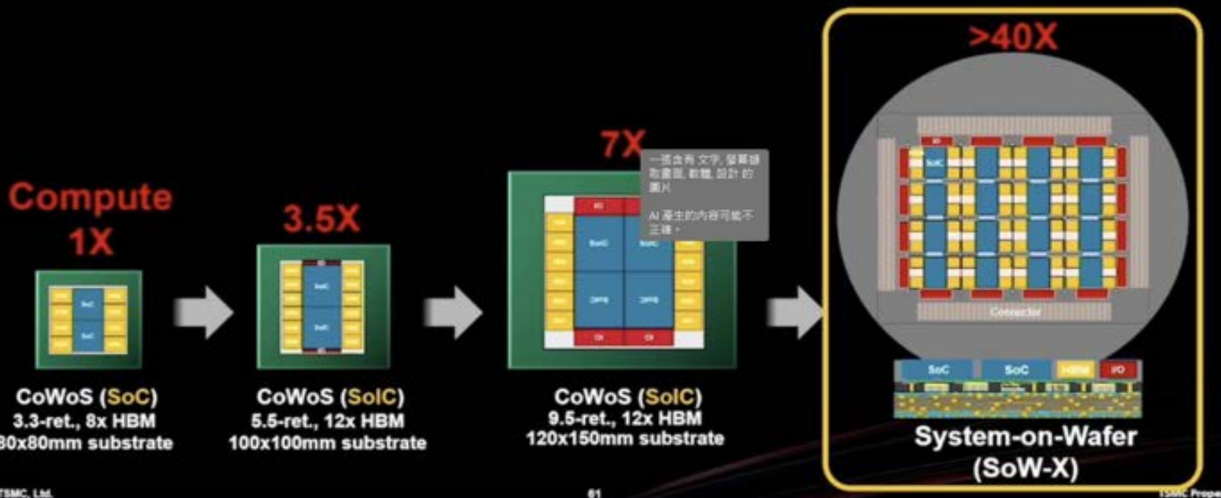
2022-2026 Expansion Capacity CAGR



AI Testing	CoWoS®	TSMC-SoIC®
80+%	80+%	100+%

TSMC-SoW™ (System-on-Wafer) Boosts AI Compute

- Wafer-scale integration maximizes computing power
- SoW-X technology for wafer-scale logic and HBM integration will be ready in 2027



CoWoS (SoC)
3.3-ret., 8x HBM
80x80mm substrate

CoWoS (SoIC)
5.5-ret., 12x HBM
100x100mm substrate

CoWoS (SoIC)
9.5-ret., 12x HBM
120x150mm substrate

System-on-Wafer (SoW-X)

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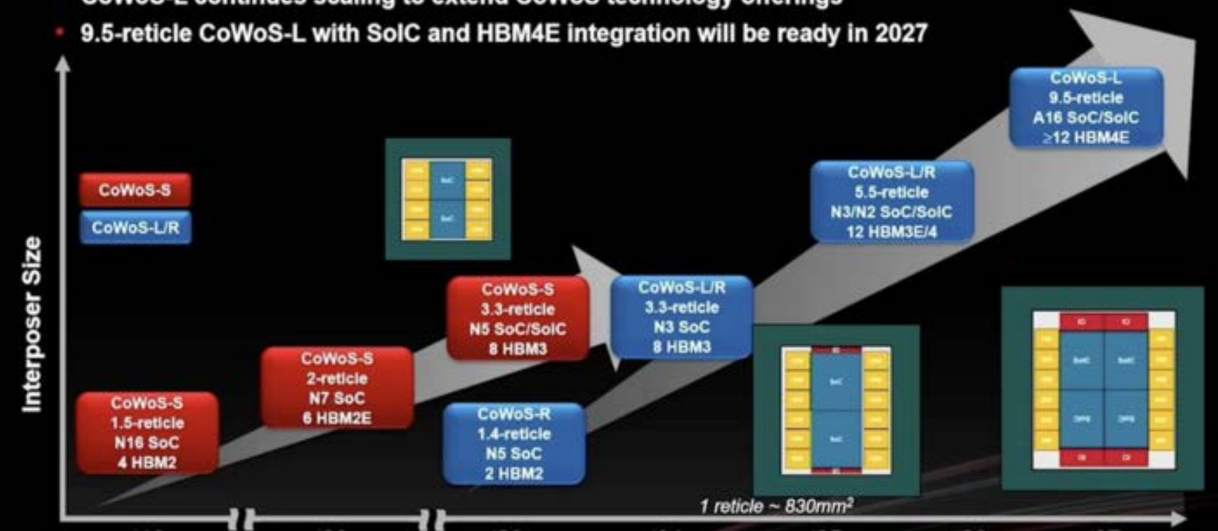
TSMC Property

CoWoS® Enables AI Compute Scaling

- CoWoS-S has been in production for over 10 years with interposer size up to 3.3-reticle
- CoWoS-L continues scaling to extend CoWoS technology offerings
- 9.5-reticle CoWoS-L with SoIC and HBM4E integration will be ready in 2027



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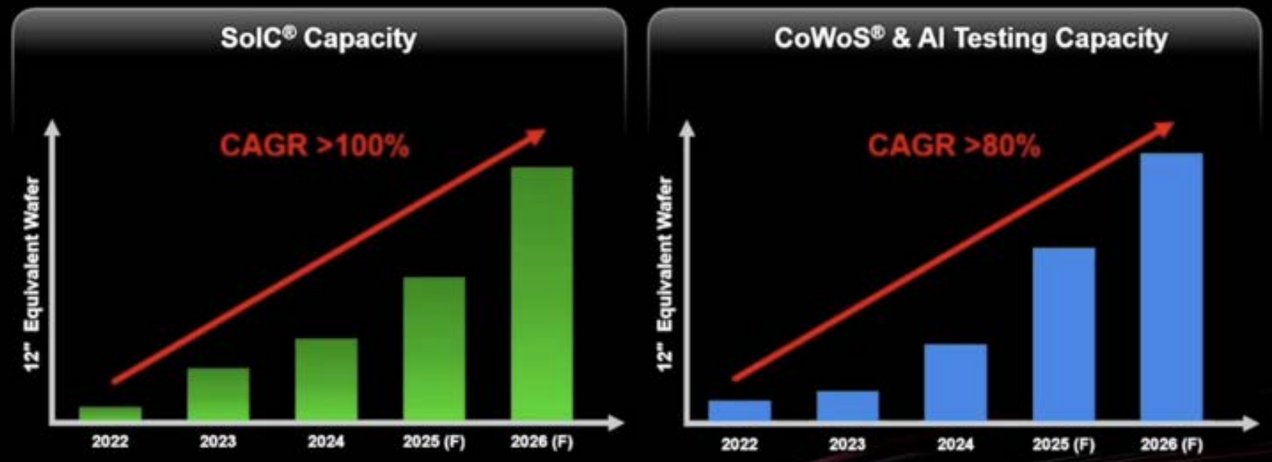
TSMC Property

TSMC 3DFabric® Capacity Growth

- Accelerating 3DFabric™ capacity expansion to support explosive HPC/AI demand



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TSMC Property

Company Introduction

2023 、2024
TSMC Award

Employee and Family
Shareholding >40%

Establishment: 1966.9.28
Capital: NT$1.56 billion
Chairman: Morrison Liang
President: Frank Liang

Shifting Trade Dynamics: Tariffs and FX Volatility

FOB TRANSACTION

Past 3 Years

Key Customer
Transaction Currency

USD backlog
≈ 10% of total orders

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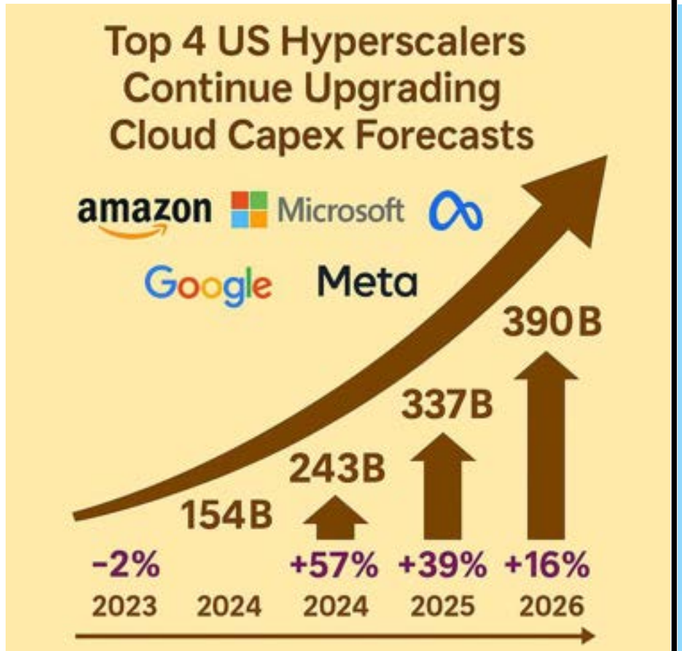
Business goals continue and follow the technological development of leading customers



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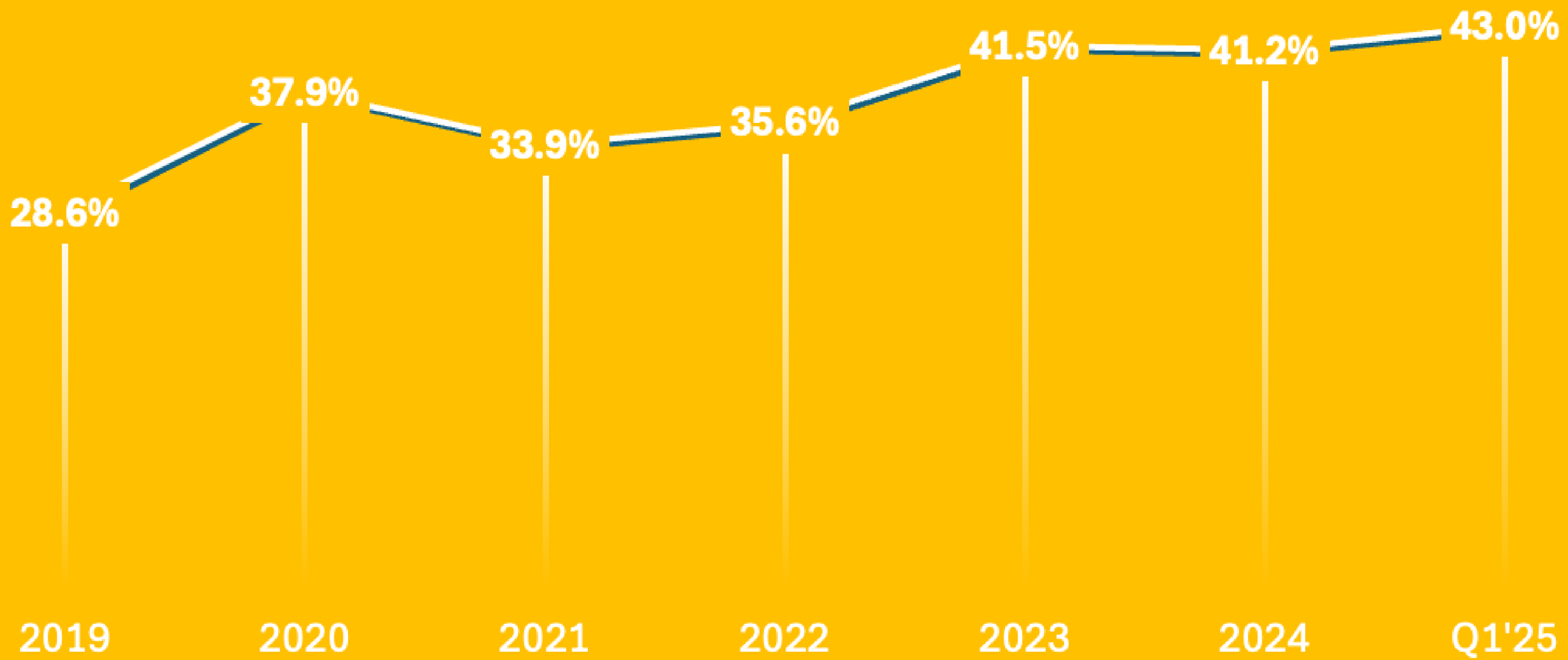
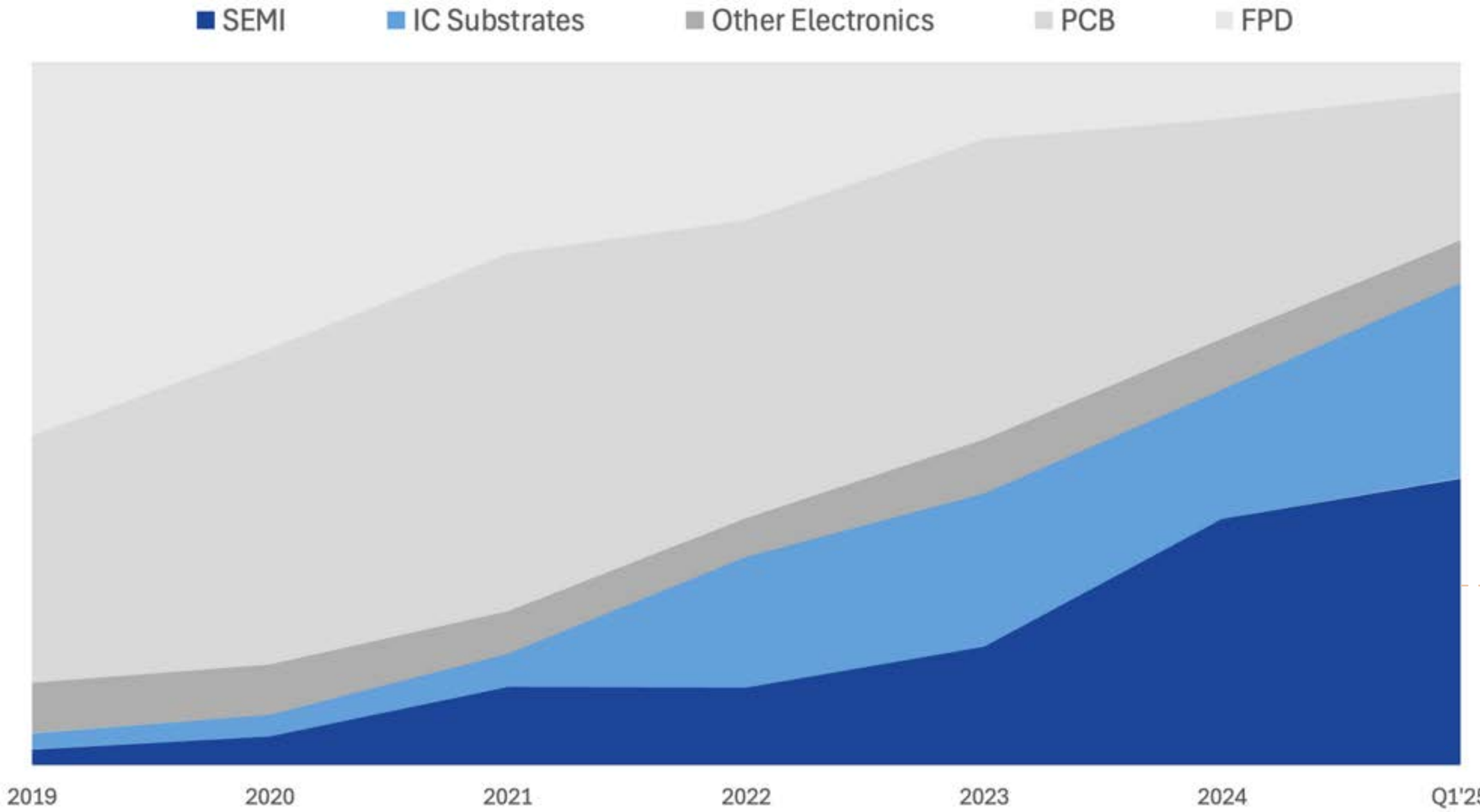
Financial Review

Selected Items from Statements of Comprehensive Income *(In NT$ millions unless otherwise noted)*	1Q25	4Q24	1Q24	QoQ	YoY
Revenue-Consolidated	1,309	1,335	1,080	-2.0%	21.2%
Gross Margin%	43.0%	41.9%	43.2%	+1.1ppts	-0.2ppts
Operating Expense	(383)	(336)	(312)	14%	23%
Operating Expense%	29.2%	25.1%	28.9%	+4.1ppts	+0.3ppts
Operating Margin%	13.8%	16.7%	14.3%	-2.9ppts	-0.5ppts
Non-Operating Items	59	77	86	-23%	-31%
Net Income Attributable to Shareholders of the Parent Company	150	195	172	-23%	-13%
Net Profit Margin%	11.5%	14.6%	15.9%	-3.1ppts	-4.4ppts
EPS (NT$D)	1	1.3	1.15	-23%	-13%

Gross Margin Rate



Revenue Composition



SEMI~40%

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OSATs’ Revenue Composition Growth

TOP 10 OSATs Are All Customers of G2C+

4 ▮▮▮▮ 10%

%

ASE Amkor Technology JCET TF通富微電 PTI HUA TIAN

KYEC ChipMOS CHIPBOND 頎邦科技

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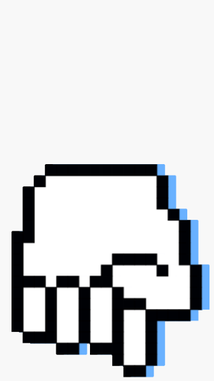
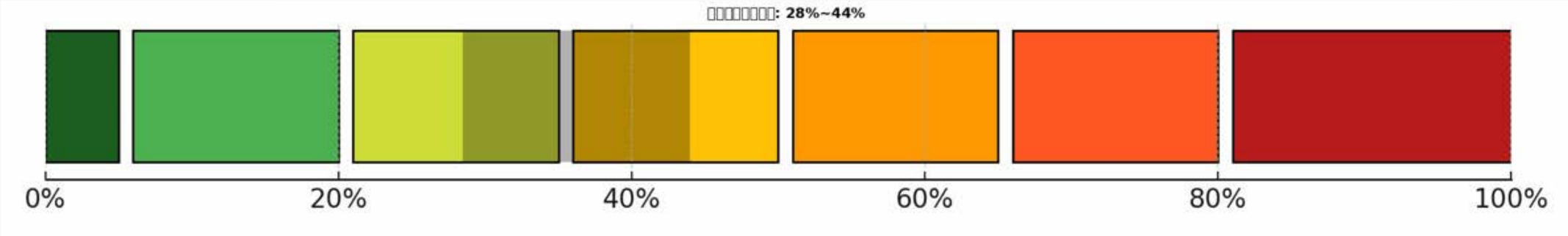
Focusing
AI 聚焦
HBM
oS
LPO
Assembly
IC Substrate
CoW
SoC/SoIC
CPO
Test
Mother Board
2024
>50%

The 12th Corporate Governance Evaluation



Protecting Shareholder Rights

Strengthening Board Structure



Enhancing Information Transparency

Promoting Sustainable Development

G2C+

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Exhibition Preview

SEMICON® SOUTHEAST ASIA 30 YEARS Special Edition

MAY 20-22, 2025 10:00~17:00 SGT

SANDS EXPO & CONVENTION CENTRE SINGAPORE

BASEMENT 2

B1524

We sincerely invite you to visit our exhibition booth for inquiries. Our team will be there to introduce our comprehensive smart solutions, aiming to enhance production line efficiency and create business opportunities.

ECTC 75 2025

The 2025 IEEE 75th Electronic Components and Technology Conference

May 27 – 30, 2025

Gaylord Texan Resort & Convention Center Dallas, Texas, USA

Booth No. 111

We sincerely invite you to visit our exhibition booth for inquiries. Our team will be there to introduce our comprehensive smart solutions, aiming to enhance production line efficiency and create business opportunities.

Invitation

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A G2C+ Alliance Company

Thank you for your attention